

## Abstract

Electromechanical connection between electronic switching  
systems and substrates, and method for producing this  
5 connection

In an electromechanical connection between electronic  
circuit systems (10) and substrates (20), these  
components are mechanically connected fixedly to one  
10 another, their electrical connection elements (11, 21)  
are connected to one another in an electrically  
conductive manner via microcapsules (23-1, 23-2), which  
comprise grains (23-1) which are coated with a dielectric  
(23-2) and, at least in part, are electrically  
15 conductive, and there is an electrically conductive  
soldered joint (25 to 28) between microcapsules (23-1,  
23-2) with broken-open dielectric (23-2) and the  
electrical connection elements (11, 21).

20 Figure 4

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20250-28881001